

# SOT1915-2

FBGA525, fine-pitch ball grid array package; 525 balls, 0.8 mm pitch, 19 mm x 19 mm x 2.37 mm body

12 December 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	FBGA525
<b>Package type industry code</b>	FBGA525
<b>Package style descriptive code</b>	FBGA (fine-pitch ball grid array)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	17-10-2018
<b>Manufacturer package code</b>	98ASA01075D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	19	-	mm
package width	-	19	-	mm
seated height	-	2.37	-	mm
nominal pitch	-	0.8	-	mm
actual quantity of termination	-	525	-	



## 2 Package outline

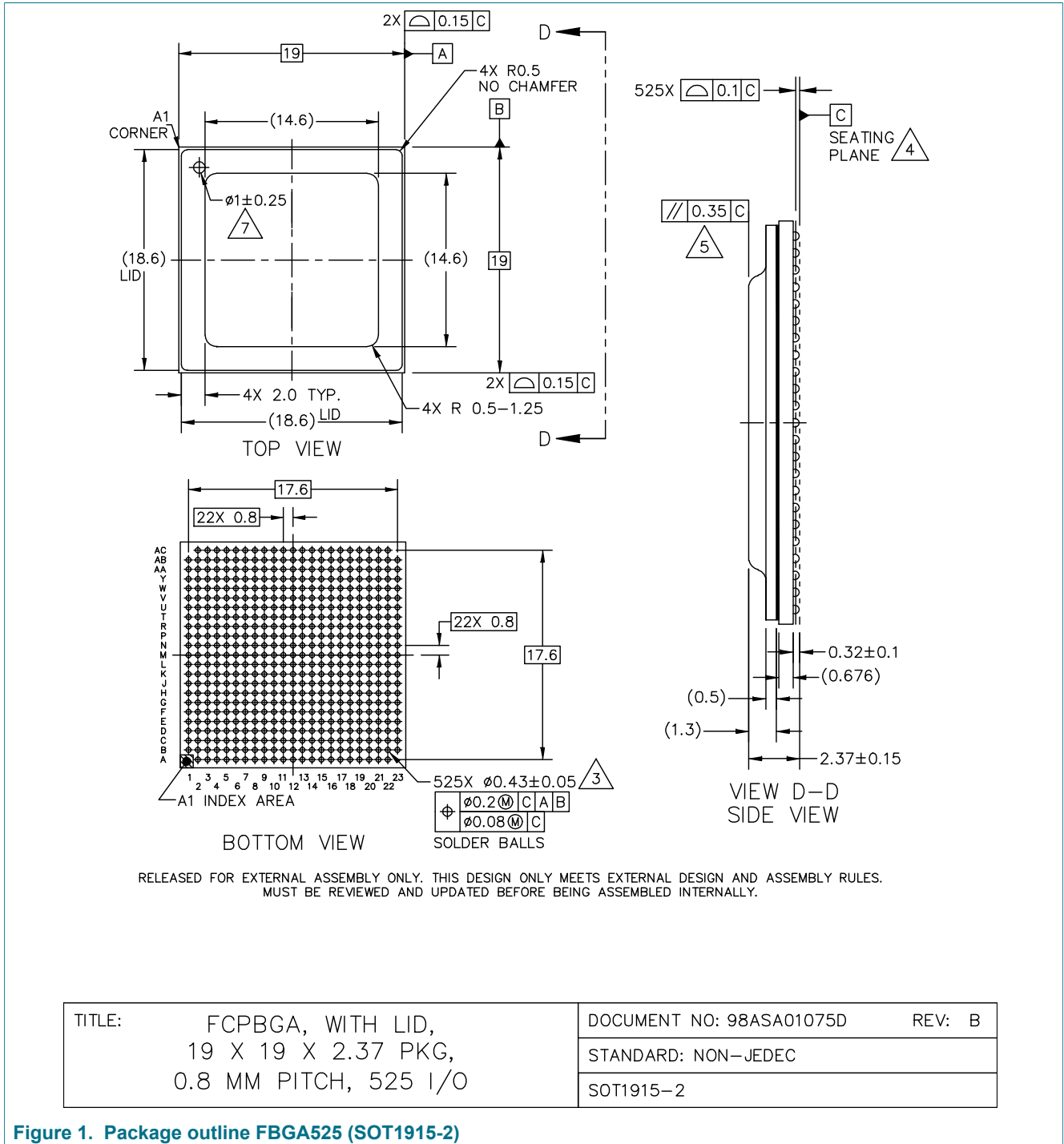


Figure 1. Package outline FBGA525 (SOT1915-2)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C. RAW BALL DIAMETER IS 0.4MM.
4. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.
6. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.
7. PIN 1 THRU HOLE SHALL BE CENTERED WITHIN THE FOOT AREA.
8. LID OVERHANG ON SUBSTRATE NOT ALLOWED.

TITLE: FCPBGA, WITH LID, 19 X 19 X 2.37 PKG, 0.8 MM PITCH, 525 I/O	DOCUMENT NO: 98ASA01075D	REV: B
	STANDARD: NON-JEDEC	
	SOT1915-2	

Figure 2. Package outline note FBGA525 (SOT1915-2)

### 3 Legal information

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Contents

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1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....4